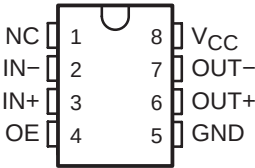


- Operates From a Single 5-V Supply
- 0-V to 5.5-V Common-Mode Input Voltage Range
- Self-Biased Inputs
- Complementary 3-State Outputs
- Enable Capability
- Hysteresis . . . 5 mV Typ
- Response Times . . . 25 ns Typ

D, P, PS, OR PW PACKAGE
(TOP VIEW)



NC—No internal connection

description/ordering information

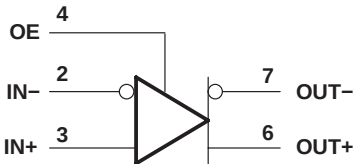
The TL712 is a high-speed comparator fabricated with bipolar Schottky process technology. The circuit has differential analog inputs and complementary 3-state TTL-compatible logic outputs with symmetrical switching characteristics. When the output enable (OE) is low, both outputs are in the high-impedance state. This device operates from a single 5-V supply and is useful as a disk memory read-chain data comparator.

ORDERING INFORMATION

T _A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	PDIP (P)	Tube of 50	TL712CP	TL712CP
	SOIC (D)	Tube of 75	TL712CD	TL712C
		Reel of 2500	TL712CDR	
	SOP (PS)	Reel of 2000	TL712CPSR	T712
	TSSOP (PW)	Tube of 150	TL712CPW	T712
		Reel of 2000	TL712CPWR	

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

symbol (positive logic)



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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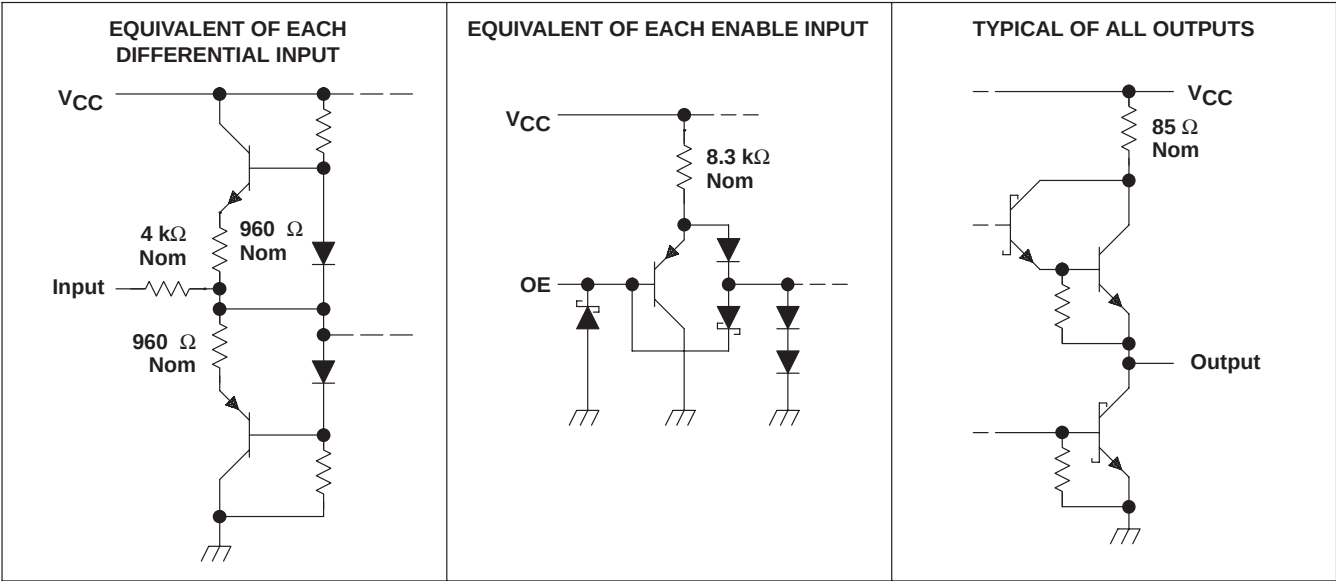
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TL712

DIFFERENTIAL COMPARATOR

SLCS002D – JUNE 1983 – REVISED AUGUST 2003

schematics of inputs and outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V _{CC} (see Note 1)	7 V
Differential input voltage, V _{ID} (see Note 2)	±25 V
Input voltage, V _I , any differential input	±25 V
Output enable voltage	7 V
Low-level output current, I _{OL}	50 mA
Package thermal impedance, θ _{JA} (see Notes 3 and 4):	
D package	97°C/W
P package	85°C/W
PS package	95°C/W
PW package	149°C/W
Operating virtual junction temperature, T _J	150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the “recommended operating conditions” section of this specification is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, except differential voltages, are with respect to the network ground.
2. Differential voltage values are at IN+ with respect to IN–.
3. Maximum power dissipation is a function of T_J(max), θ_{JA}, and T_A. The maximum allowable power dissipation at any allowable ambient temperature is P_D = (T_J(max) – T_A)/θ_{JA}. Operating at the absolute maximum T_J of 150°C can affect reliability.
4. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions

	MIN	NOM	MAX	UNIT
V _{CC} Supply voltage	4.75	5	5.25	V
V _{IC} Common-mode input voltage	0		5.5	V
I _{OH} High-level output current			–1	mA
I _{OL} Low-level output current			16	mA
T _A Operating free-air temperature	0		70	°C

electrical characteristics at V_{CC} = 5 V, T_A = 25°C

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
V _T Threshold voltage (V _{T+} and V _{T–})	V _{ICR} = 0 to 5 V	–100 [†]		100	mV
V _{hys} Hysteresis (V _{T+} – V _{T–})			5		mV
V _{OH} High-level output voltage	V _{ID} = 100 mV, I _{OH} = –1 mA	2.7	3.5		V
V _{OL} Low-level output voltage	V _{ID} = –100 mV, I _{OL} = 16 mA		0.4	0.5	V
I _{OZ} Off-state output current	V _O = 2.4 V			–20	μA
I _I Enable current	V _I = 5.5 V			100	μA
I _{IH} High-level enable current	V _{IH} = 2.7 V			20	μA
I _{IL} Low-level enable current	V _{IL} = 0.4 V			–360	μA
r _i Differential input resistance		4			kΩ
r _o Output resistance				100	Ω
I _{OS} Short-circuit output current		–15		–85	mA
I _{CC} Supply current	V _{ID} = 0, No load		17	20	mA

[†] The algebraic convention, where the more-negative limit is designated as minimum, is used in this data sheet for input threshold voltage levels only.

switching characteristics, V_{CC} = 5 V, T_A = 25°C

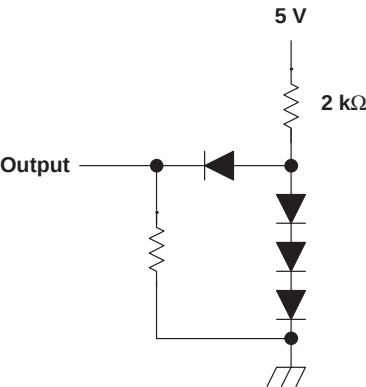
PARAMETER	TEST CONDITIONS	TYP	UNIT
t _{PLH} Propagation delay time, low-to-high-level output	TTL load, See Note 5 and Figure 1	25	ns
t _{PHL} Propagation delay time, high-to-low-level output		25	ns

NOTE 5: The response time specified is for a 100-mV input step with 5-mV overdrive (105 mV total) and is the interval between the input step function and the instant when the output crosses 2.5 V.

TL712
DIFFERENTIAL COMPARATOR

SLCS002D – JUNE 1983 – REVISED AUGUST 2003

PARAMETER MEASUREMENT INFORMATION



NOTE A: All diodes are 1N4148 or equivalent.

Figure 1. TTL Output Load Circuit

TYPICAL CHARACTERISTICS

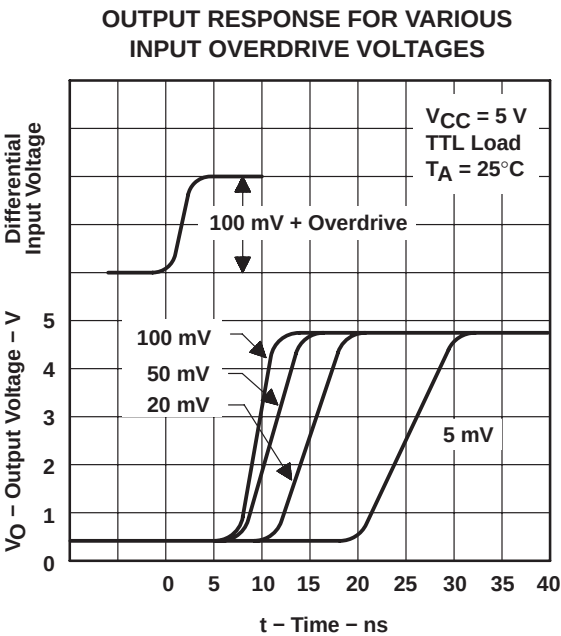


Figure 2

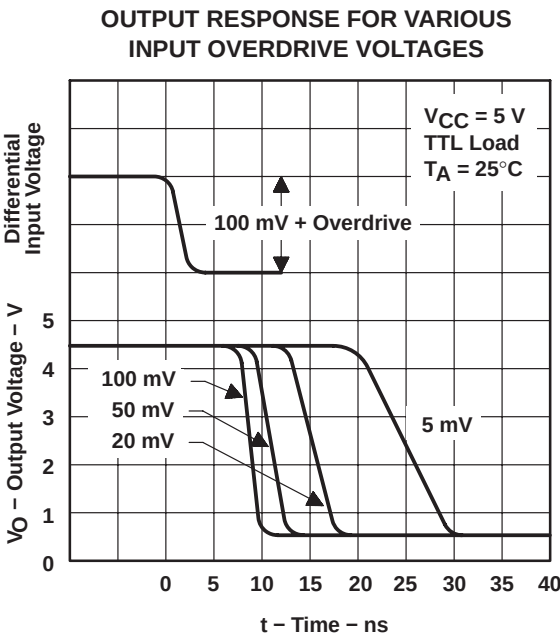


Figure 3

TYPICAL CHARACTERISTICS

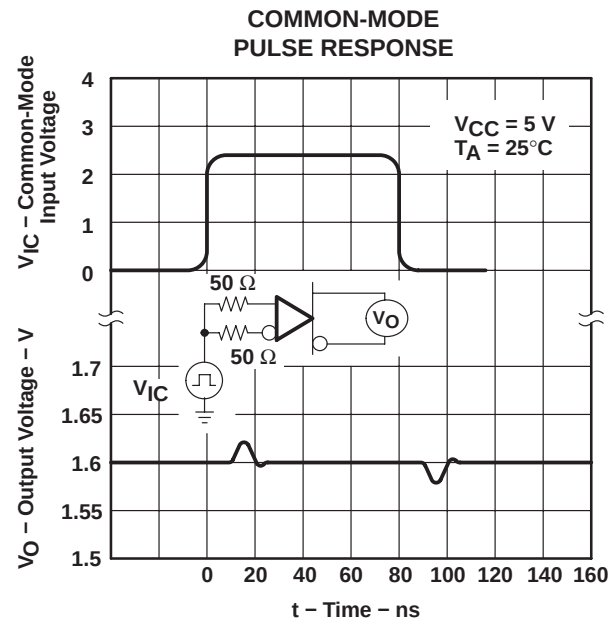


Figure 4

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TL712CD	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TL712C
TL712CD.A	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TL712C
TL712CDG4	Active	Production	SOIC (D) 8	75 TUBE	-	Call TI	Call TI	0 to 70	
TL712CDR	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TL712C
TL712CDR.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	TL712C
TL712CP	Active	Production	PDIP (P) 8	50 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	TL712CP
TL712CP.A	Active	Production	PDIP (P) 8	50 TUBE	Yes	NIPDAU	N/A for Pkg Type	0 to 70	TL712CP
TL712CPSR	Active	Production	SO (PS) 8	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	T712
TL712CPSR.A	Active	Production	SO (PS) 8	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	T712
TL712CPWR	Active	Production	TSSOP (PW) 8	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	T712
TL712CPWR.A	Active	Production	TSSOP (PW) 8	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	T712

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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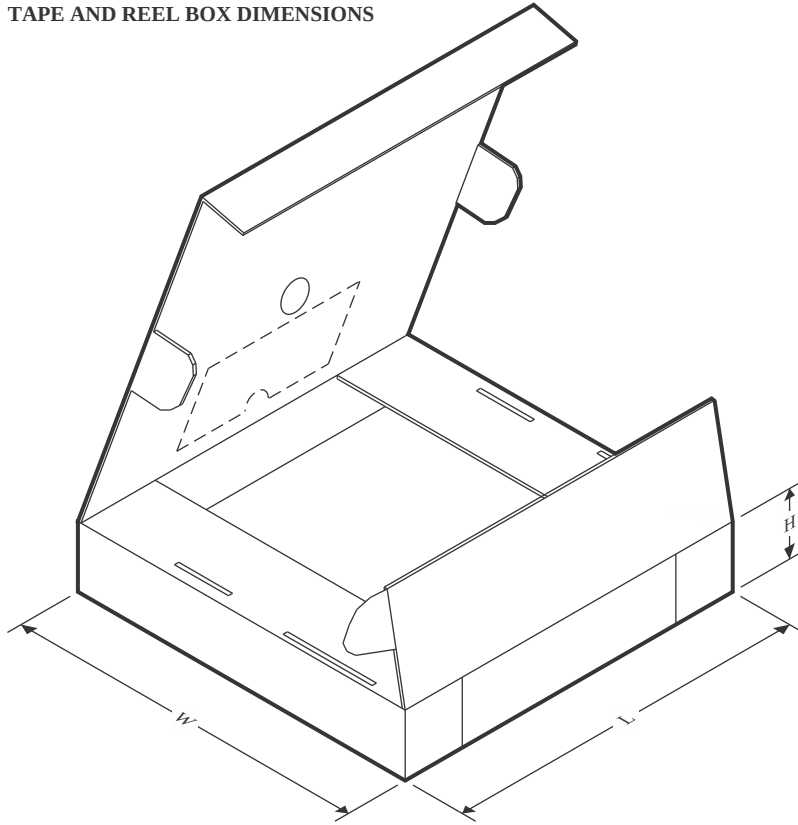
TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL712CDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL712CPSR	SO	PS	8	2000	330.0	16.4	8.35	6.6	2.4	12.0	16.0	Q1
TL712CPWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL712CDR	SOIC	D	8	2500	353.0	353.0	32.0
TL712CPSR	SO	PS	8	2000	356.0	356.0	35.0
TL712CPWR	TSSOP	PW	8	2000	356.0	356.0	35.0

TUBE


*All dimensions are nominal

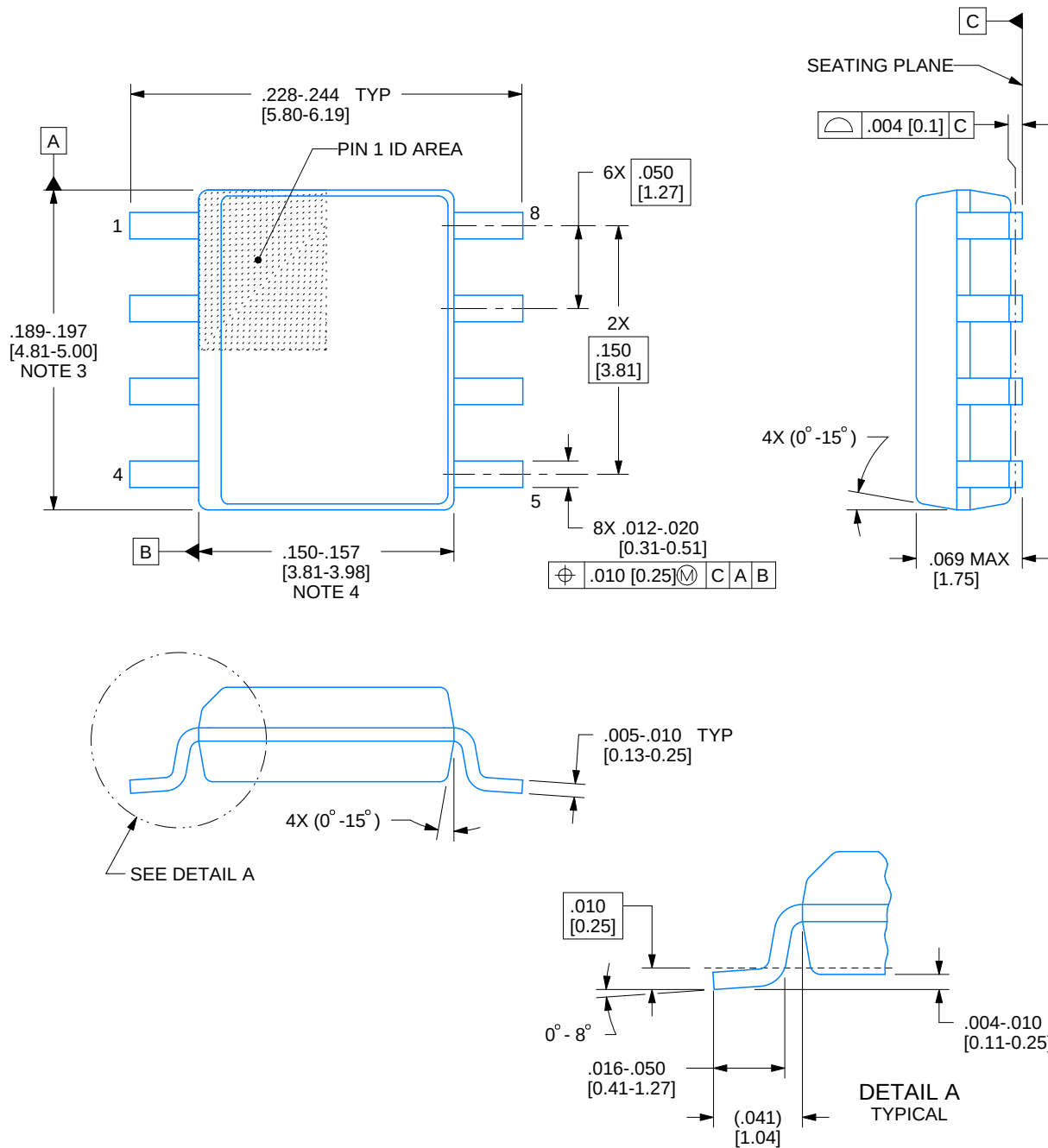
Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
TL712CD	D	SOIC	8	75	507	8	3940	4.32
TL712CD.A	D	SOIC	8	75	507	8	3940	4.32
TL712CP	P	PDIP	8	50	506	13.97	11230	4.32
TL712CP.A	P	PDIP	8	50	506	13.97	11230	4.32

D0008A

PACKAGE OUTLINE

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



4214825/C 02/2019

NOTES:

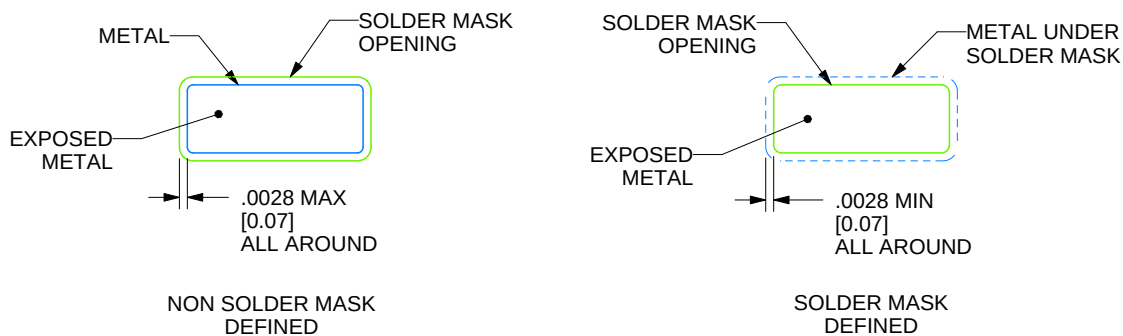
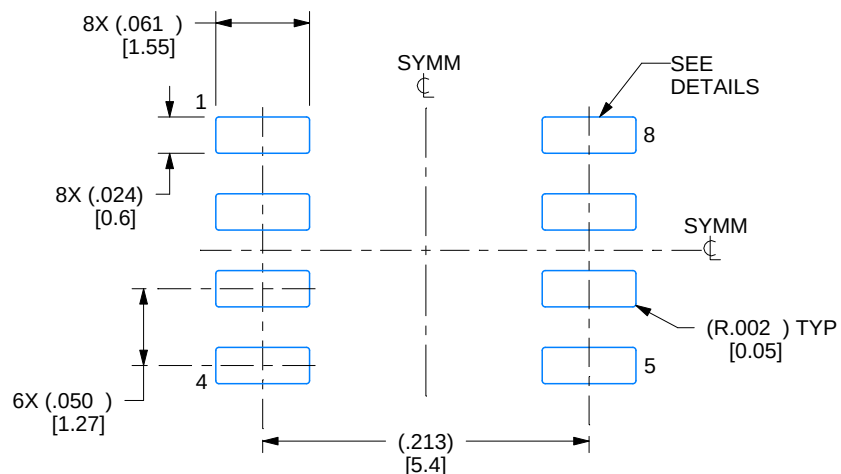
1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
4. This dimension does not include interlead flash.
5. Reference JEDEC registration MS-012, variation AA.

EXAMPLE BOARD LAYOUT

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



4214825/C 02/2019

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

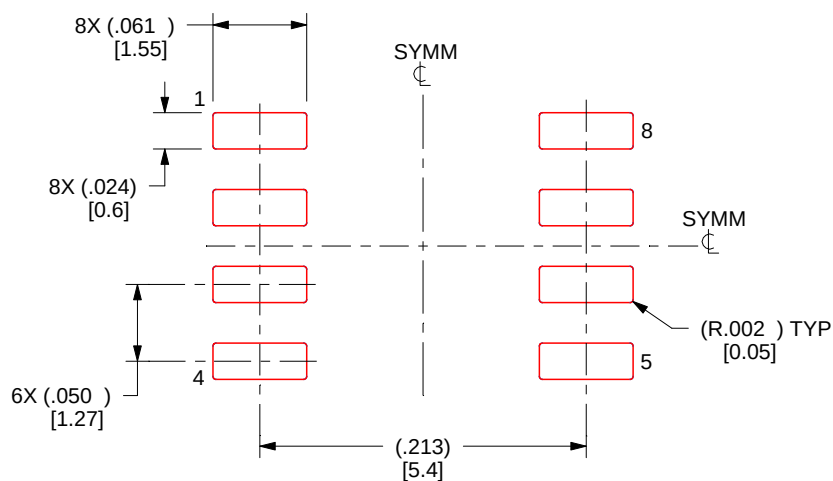
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
BASED ON .005 INCH [0.125 MM] THICK STENCIL
SCALE:8X

4214825/C 02/2019

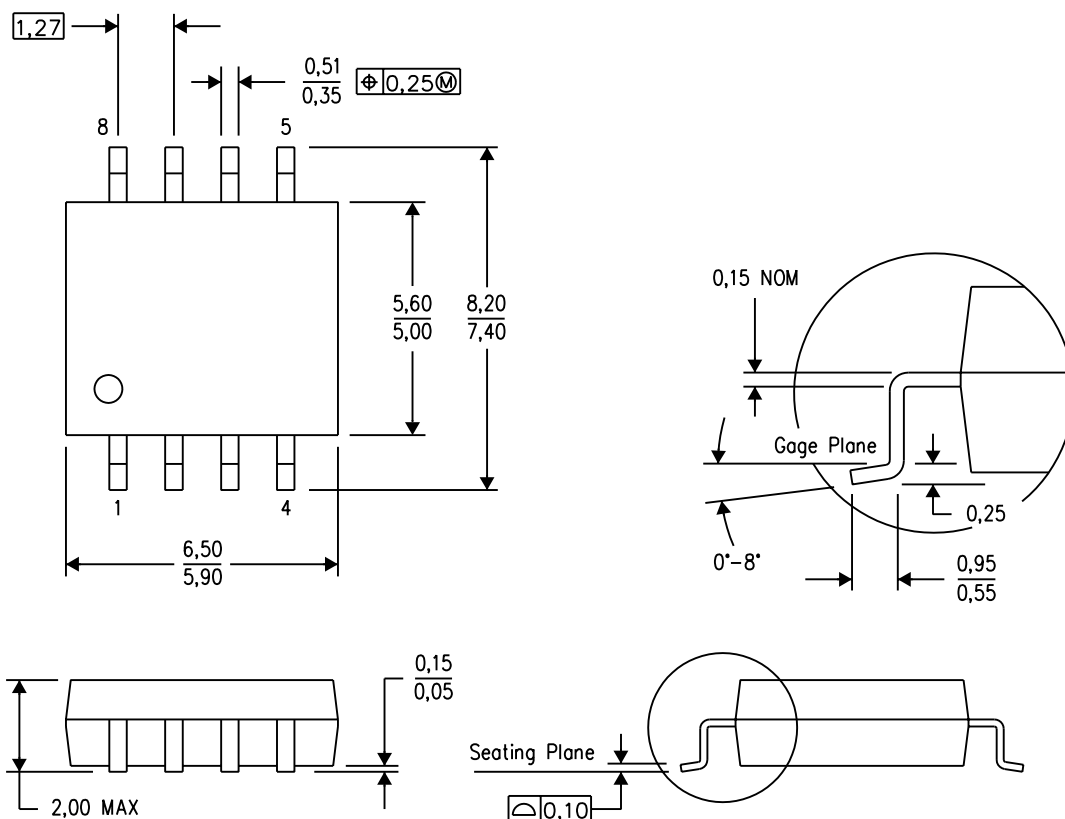
NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

MECHANICAL DATA

PS (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE

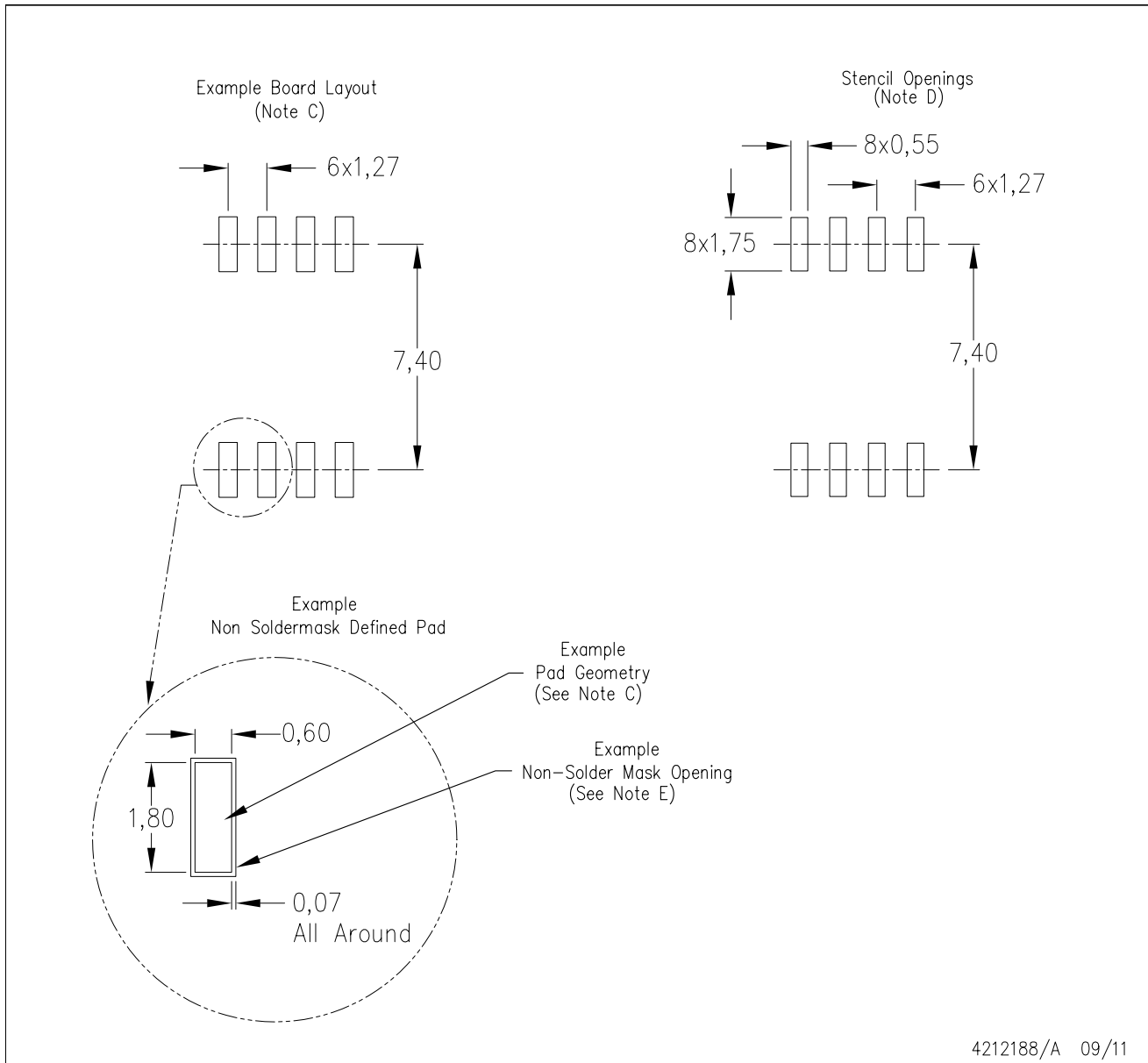


4040063/C 03/03

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

PS (R-PDSO-G8)

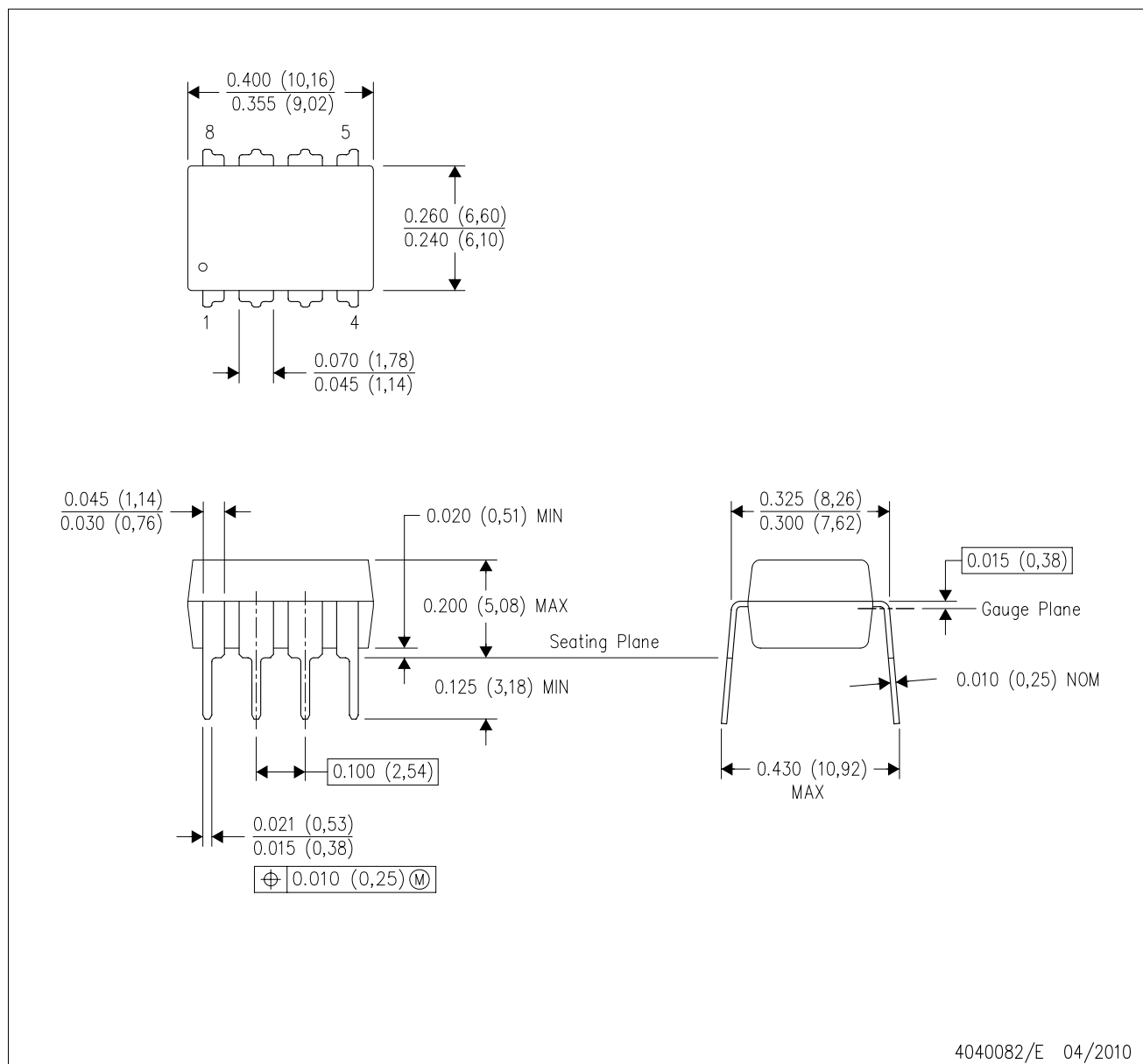
PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE



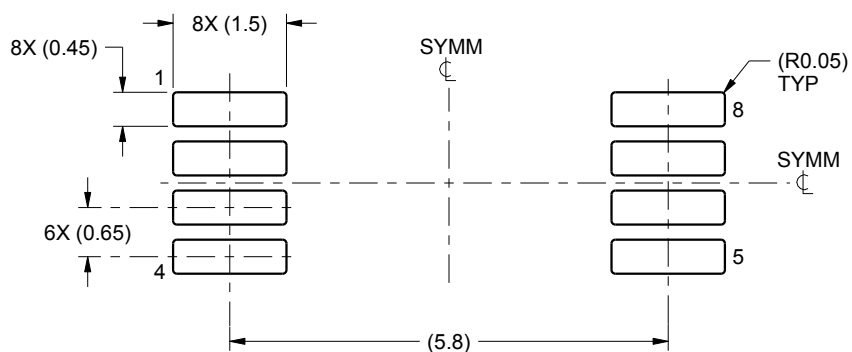
- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Falls within JEDEC MS-001 variation BA.

EXAMPLE BOARD LAYOUT

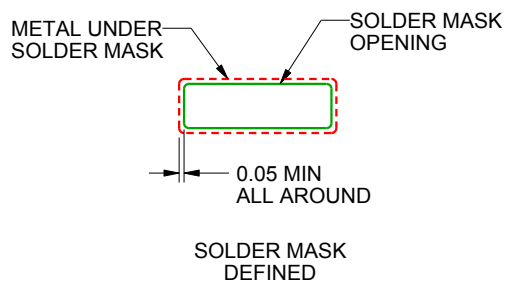
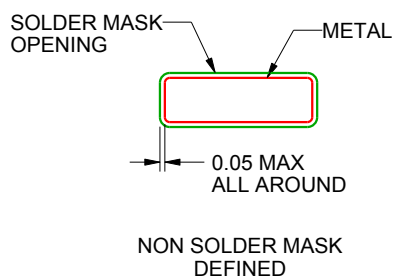
PW0008A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
SCALE:10X



SOLDER MASK DETAILS
NOT TO SCALE

4221848/A 02/2015

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

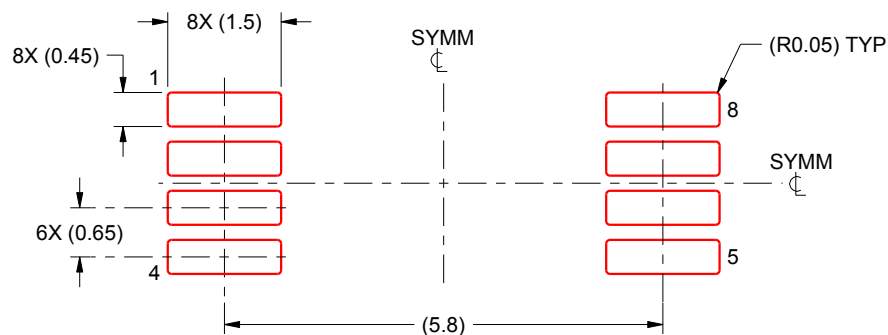
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0008A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:10X

4221848/A 02/2015

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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